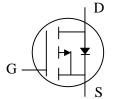


P-channel Enhancement-mode Power MOSFET

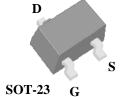
Simple Drive Requirement
Small Package Outline
Surface Mount Device
RoHS-compliant, Halogen-free



BV _{DSS}	-20V
R _{DS(ON)}	$52\text{m}\Omega$
I _D	-4.2A

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, low on-resistance and cost-effectiveness.



The AP2317GN-HF-3 is in the popular SOT-23 small surface-mount package which is widely used in commercial and industrial applications where a small board footprint is required.

This device is well suited for use in medium current applications such as load switches.

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	±8	V
I _D at T _A =25°C	Continuous Drain Current 3	-4.2	А
I _D at T _A = 70°C	Continuous Drain Current ³	-3.4	А
I _{DM}	Pulsed Drain Current ¹	-16	А
P _D at T _A =25°C	Total Power Dissipation	1.38	W
	Linear Derating Factor	0.01	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Unit
Rthj-a	Maximum Thermal Resistance, Junction-ambient	90	°C/W

Ordering Information

AP2317GN-HF-3: in RoHS-compliant, halogen-free SOT-23, shipped on tape and reel, 3000pcs/reel

Electrical Specifications at T_i=25°C (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V, I_D =-250uA	-20	-	-	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-4.5V, I _D =-4A	-	-	52	mΩ
		V_{GS} =-2.5V, I_{D} =-3A	-	-	65	mΩ
		V _{GS} =-1.8V, I _D =-1A	-	-	90	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{D}=-250uA$	-0.3	-	-1	V
g _{fs}	Forward Transconductance	V_{DS} =-5V, I_{D} =-4A	-	7	-	S
I _{DSS}	Drain-Source Leakage Current	V_{DS} =-16V, V_{GS} =0V	-	-	-1	uA
	Drain-Source Leakage Current (T _j =55°C)	V_{DS} =-16V, V_{GS} =0V	-	-	-10	uA
I _{GSS}	Gate-Source Leakage	$V_{GS}=\pm 8V$, $V_{DS}=0V$	1	-	±100	nA
Q_g	Total Gate Charge ²	I _D =-4A	•	13	21	nC
Q_{gs}	Gate-Source Charge	V _{DS} =-10V	1	1.8	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V _{GS} =-4.5V	-	4.7	-	nC
t _{d(on)}	Turn-on Delay Time ²	V _{DS} =-10V	-	10	-	ns
t _r	Rise Time	I _D =-1A	•	18	-	ns
t _{d(off)}	Turn-off Delay Time	$R_G=3.3\Omega$, $V_{GS}=-5V$	-	23	-	ns
t _f	Fall Time	$R_D=10\Omega$	-	31		ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	1030	1650	pF
C _{oss}	Output Capacitance	V_{DS} =-20V	-	120	-	рF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	105	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V_{SD}	Forward On Voltage ²	I _S =-1.2A, V _{GS} =0V	-	-	-1.2	V
trr	Reverse Recovery Time ²	I _S =-4A, V _{GS} =0V,	-	27	-	ns
Qrr	Reverse Recovery Charge	dl/dt=100A/µs	-	15	-	nC

Notes:

- 1. Pulse width limited by maximum junction temperature.
- 2. Pulse test pulse width \leq 300 μ s , duty cycle \leq 2%
- 3. Surface mounted on 1 in²copper pad of FR4 board, t ≤10sec; 270°C/W when mounted on minimum copper pad.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

APEC RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.

Typical Electrical Characteristics

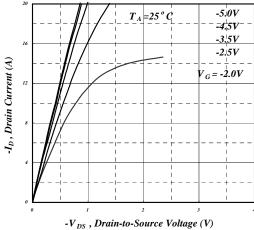
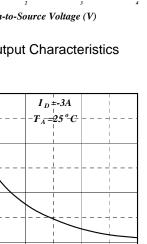
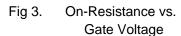


Fig 1. Typical Output Characteristics



- V_{GS} , Gate-to-Source Voltage (V)



 $R_{DS(ON)}\left(\Omega\right)$

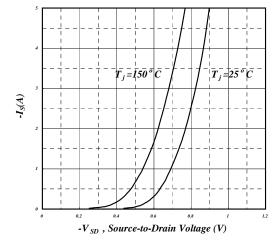


Fig 5. Forward Characteristic of Reverse Diode

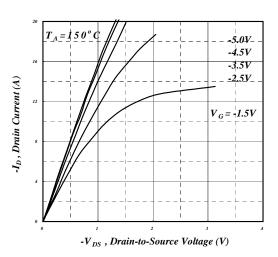


Fig 2. Typical Output Characteristics

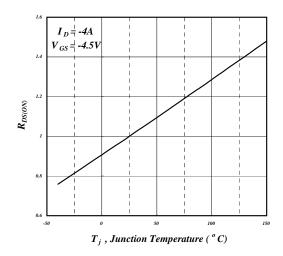


Fig 4. Normalized On-Resistance vs. Junction Temperature

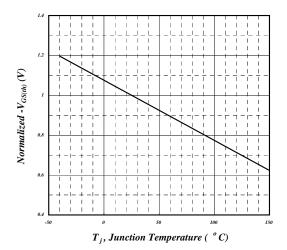


Fig 6. Gate Threshold Voltage vs. Junction Temperature

Typical Electrical Characteristics (cont.)

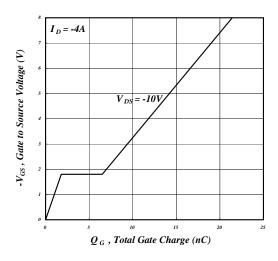


Fig 7. Gate Charge Characteristics

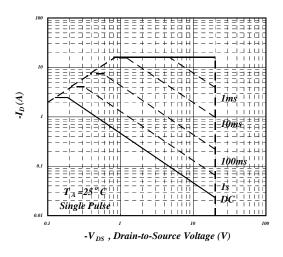


Fig 9. Maximum Safe Operating Area

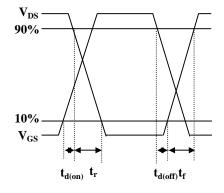


Fig 11. Switching Time Circuit

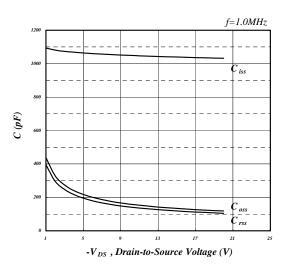


Fig 8. Typical Capacitance Characteristics

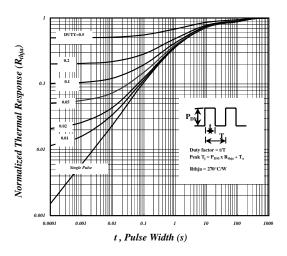


Fig 10. Effective Transient Thermal Impledance

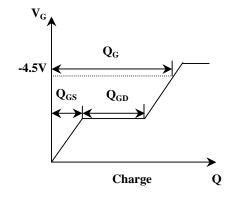
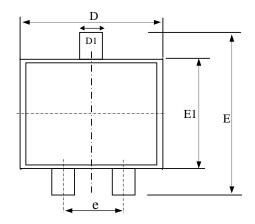
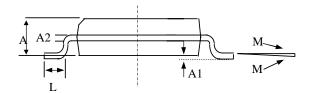


Fig 12. Gate Charge Waveform

Package Dimensions: SOT-23





SYMBOLS	Millimeters			
	MIN	NOM	MAX	
A	0.88		1.30	
A1	0.00		0.10	
A2	0.08		0.25	
D1	0.30	0.40	0.50	
e	1.70	2.00	2.30	
D	2.70	2.90	3.10	
Е	2.20	2.60	3.00	
E1	1.20	1.50	1.80	
M	0°		10°	
L	0.30		0.60	

- 1. All dimensions are in millimeters.
- 2. Dimensions do not include mold protrusions.

Marking Information:

